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(71)Applicant : TEXAS INSTR INC <TI>

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(72)Inventor : HEMPEL JR EUGENE O

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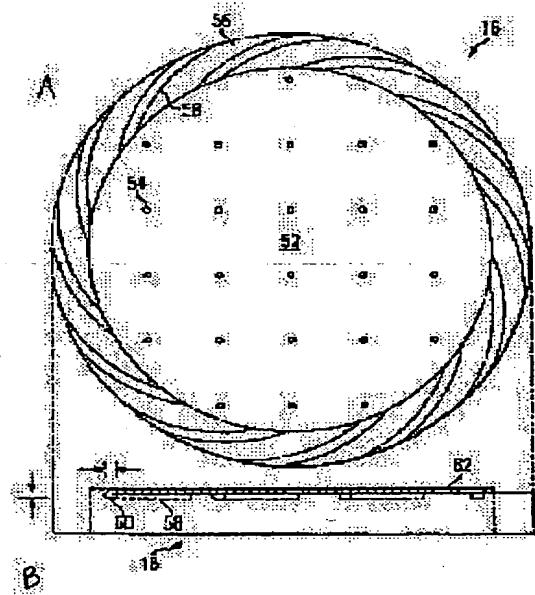
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(54) WAFER POLISHING SUPPORT, CHEMICAL-MECHANICAL POLISHING DEVICE AND METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To enable a semiconductor wafer to be uniformly polished and enhanced in polish throughput by a method wherein a slurry path is carefully provided to the outer edge of a wafer support, and a flow of slurry applied to an interface between the wafer and a pad is enhanced in flow rate.

SOLUTION: A support 16 includes an outer edge 56 which surrounds a wafer-holding plane 52, and the outer edge 56 includes wafer paths 58. The wafer paths 58 are spiraled to send slurry to an interface between a semiconductor wafer and a conditional pad. As the slurry paths 58 are cured, they function as jets to draw in slurry, and slurry is forcibly sent between the semiconductor wafer and the conditional pad. The slurry paths 58 are distributed in the outer edge 56 so as to introduce slurry uniformly to an interface between the wafer and the pad. By this setup, a semiconductor wafer can be uniformly polished and enhanced in polish throughput.



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